

Appl. No. 10/675,049 Amdt. dated 5/15/06  
Reply to Office action of February 16, 2006

SPECIFICATION AMENDMENTS

) A new Abstract as amended appears on a separate sheet.

Please amend the Abstract as follows:

Abstract of the Disclosure:

~~The invention relates to a~~ A method and ~~to~~ a furnace are  
provided for the vapor phase deposition of components onto  
semiconductor substrates. The main flow direction of the  
process gases can be varied or reversed by the furnace in the  
course of the method. This prevents temperature and  
concentration inhomogeneities of the process gas within the  
furnace, and permits the components to be uniformly deposited  
onto the semiconductor substrates.